



32K x 9 Synchronous Cache R/W RAM

SRAMS

- Supports 50-MHz cache systems
- 32K by 9 common I/O
- BiCMOS for optimum speed/power
- 14-ns access delay (clock to output)
- Two-bit wraparound counter supporting the 486 burst sequence (7B173)
- Two-bit wraparound counter supporting the linear burst sequence (7B174)
- Separate address strobes from processor and from cache controller
- Synchronous self-timed write
- Direct interface with the processor and external cache controller

- **Two complementary synchronous chip selects**
- **Asynchronous output enable**

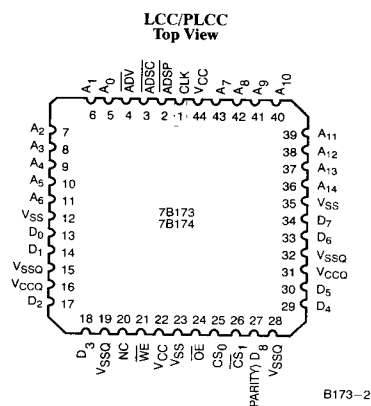
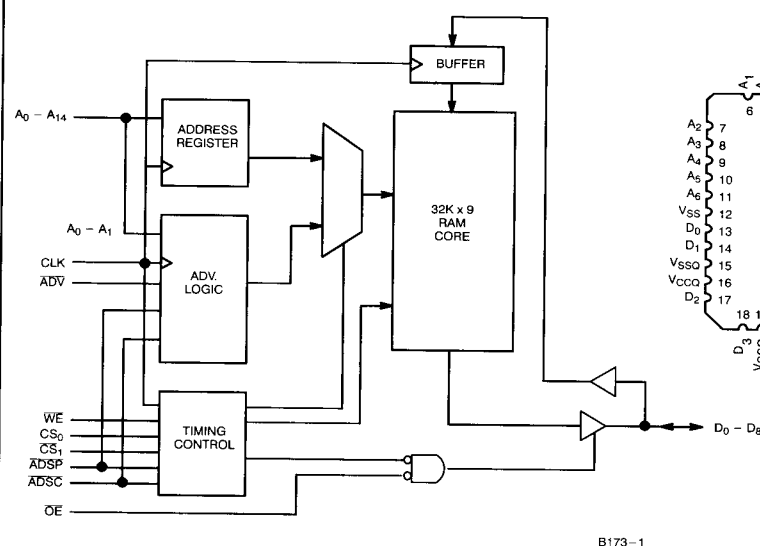
The CY7B173 and CY7B174 are 32K by 9 synchronous cache RAMs designed to interface with high-speed microprocessors with minimum glue logic. Maximum access delay from clock rise is 14 ns. A 2-bit on-chip counter captures the first address in a burst and increments the address automatically for the rest of the burst access.

The CY7B173 is designed for Intel i486-based systems; its counter follows the burst sequence of the i486. The CY7B174

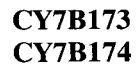
is architected for other processors with linear burst sequences. Burst accesses can be initiated with the processor address strobe ($\overline{\text{ADSP}}$) or the cache controller address strobe ($\overline{\text{ADSC}}$) inputs. Address advancement is controlled by the address advancement ($\overline{\text{ADV}}$) input.

A synchronous self-timed write mechanism is provided to simplify the write interface. Two complementary synchronous chip select inputs are provided to support two banks of memory (256 Kbytes) with no external logic. These signals, in conjunction with the asynchronous output enable ($\overline{\text{OE}}$) signal, greatly simplify memory bank selection.

Pin Configurations



		7B173-14 7B174-14	7B173-18 7B174-18	7B173-21 7B174-21
Maximum Access Time (ns)		14	18	21
Maximum Operating Current (mA)	Commercial	210	210	210
	Military		230	230



Pin Definitions

Signal Name	I/O	Description
A ₀ – A ₁₄	I	Address Inputs
CLK	I	Clock
WE	I	Write Enable
OE	I	Output Enable
CS ₀ , CS ₁	I	Chip Select
ADV	I	Address Advance
ADSP	I	Processor Address Strobe
ADSC	I	Cache Controller Address Strobe
D ₀ – D ₈	I/O	Data I/O
V _{CC}	–	+5V Power Supply
V _{SS}	–	Ground
V _{CCQ}	–	Output Buffer (Driver) Power Supply
V _{SSQ}	–	Output Buffer (Driver) Ground
RESV	–	Reserved

Pin Descriptions

Input Signals	
CLK	Clock signal used as the reference for most on-chip operations.
ADSP	Address strobe signal from the processor: ADSP is asserted when the processor address is valid. If ADSP is LOW at clock rise, the address at A ₀ through A ₁₄ will be loaded into the address register and the address advancement logic. The write signal, WE, is ignored in the clock cycle where ADSP is asserted. If both ADSP or ADSC are active at clock rise, only ADSP will be recognized.
ADSC	Address strobe signal from the cache controller: ADSC is asserted when a new address generated by the cache controller is ready to be strobed into the CY7B173/4. The write signal, WE, is recognized in the clock cycle where ADSC is asserted. If both ADSP and ADSC are active at clock rise, only ADSP will be recognized.
A ₀ – A ₁₄	Address lines: These address inputs are loaded into the address register and the address advancement logic at clock rise if ADSP or ADSC is LOW. They are used to select one of the 32K locations.
WE	Write Enable: This signal is sampled at the rising edge of the clock signal. If WE = 0, a self-timed write operation will be initiated and data on D ₀ – D ₈ will be stored into the selected memory location. The only exception occurs if both ADSP and WE are LOW at clock rise. In this case, the write signal is ignored.
ADV	Address Advance input: ADV is sampled at the rising edge of the clock. In the case of the CY7B173, LOW at this input will advance the address in the advancement logic according to the Intel 80486 burst sequence. In the case of the CY7B174, the addresses will be advanced linearly. This input is ignored if ADSP or ADSC is active (LOW).
CS ₀ – CS ₁	Chip Select inputs: CS ₀ is active HIGH and CS ₁ is active LOW. Both inputs are sampled at clock rise if ADSP or ADSC is LOW. The RAM is selected if CS ₀ = 1 and CS ₁ = 0.
OE	Output Enable: OE is an asynchronous signal that disables all output drivers (D ₀ – D ₈) when it is deasserted. OE should be deasserted during write cycles because the CY7B173/4 is a common I/O device and three-state conflict may occur at the data pins.
NC	No Connect: This input can be left floating or tied to V _{SS} or V _{CC} .
Bidirectional Signals	
D ₀ – D ₈	Data I/O lines: During a read cycle, if OE is asserted, data in the selected location will appear at these pins. During a write cycle, data presented at these pins is captured at clock rise and stored into the selected RAM location if WE is LOW. All nine outputs will be placed in a three-state condition when OE is deasserted, when the RAM is deselected via the chip select inputs, or during a write cycle.

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	– 65°C to +150°C
Ambient Temperature with Power Applied	– 55°C to +125°C
Supply Voltage on V _{CC} Relative to GND	– 0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State	– 0.5V to V _{CC} + 0.5V
DC Input Voltage ^[1]	– 0.5V to V _{CC} + 0.5V
Current into Outputs (LOW)	20 mA

Static Discharge Voltage >2001V
(per MIL-STD-883, Method 3015)

Latch-Up Current >200 mA

Operating Range

Range	Ambient Temperature ^[2]	V _{CC}
Commercial	0°C to +70°C	5V ± 10%
Military	– 55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	7B173–14 7B174–14		7B173–18, 21 7B174–18, 21		Unit
			Min.	Max.	Min.	Max.	
V _{OH}	Output HIGH Voltage	V _{CC} = Min., I _{OH} = – 4.0 mA	2.4		2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA		0.4		0.4	V
V _{IH}	Input HIGH Voltage		2.2	V _{CC}	2.2	V _{CC}	V
V _{IL}	Input LOW Voltage ^[1]		– 0.5	0.8	– 0.5	0.8	V
I _{IX}	Input Load Current	GND ≤ V _I ≤ V _{CC}	– 10	+10	– 10	+10	μA
I _{OZ}	Output Leakage Current	GND ≤ V _I ≤ V _{CC} , Output Disabled	– 100	+100	– 100	+100	μA
I _{OS}	Output Short Circuit Current ^[3]	V _{CC} = Max., V _{OUT} = GND		– 300		– 300	mA
I _{CC}	V _{CC} Operating Supply Current	V _{CC} = Max., I _{OUT} = 0 mA, f = f _{MAX} = 1/t _{RC}	Com'l	210		210	mA
			Mil			230	

Capacitance^[4]

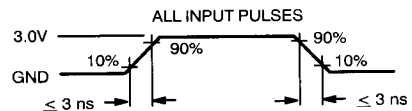
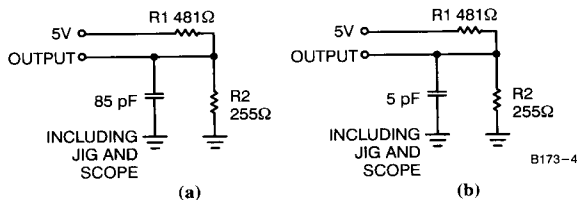
Parameter	Description	Test Conditions	Max.	Unit
C _{IN} : Addresses	Input Capacitance	T _A = 25°C, f = 1 MHz, V _{CC} = 5.0V	4.5	pF
C _{IN} : Other Inputs			6	pF
C _{OUT}	Output Capacitance		13	pF

Notes:

- V_{IL} (min.) = – 1.5V for pulse durations of less than 20 ns.
- T_A is the “instant on” case temperature.
- Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.

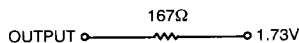
- Tested initially and after any design or process changes that may affect these parameters (PLCC package).

AC Test Loads and Waveforms



B173–5

Equivalent to: THÉVENIN EQUIVALENT



Switching Characteristics Over the Operating Range^[5]

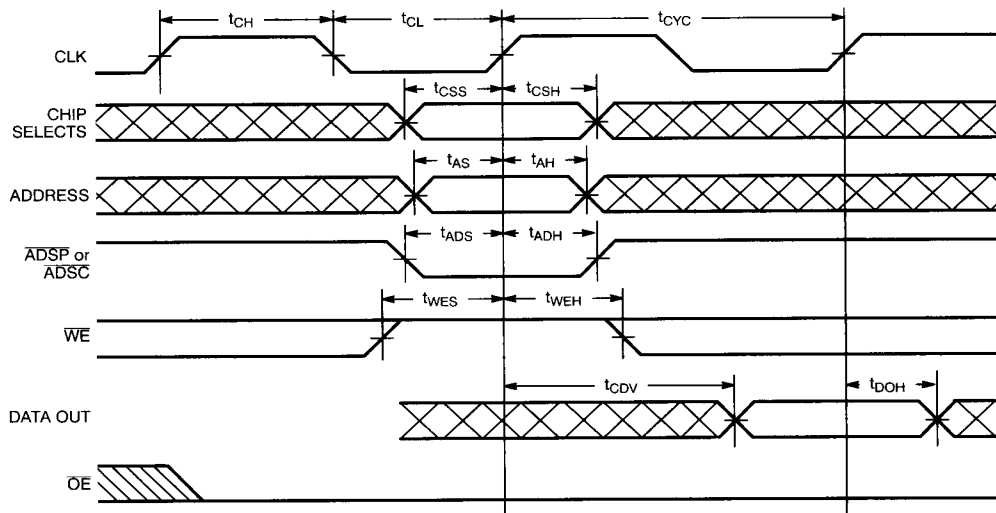
Parameter	Description	7B173–14 7B174–14		7B173–18 7B174–18		7B173–21 7B173–21		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t _{CYC}	Clock Cycle Time	20		25		30		ns
f _{MAX}	Maximum Frequency		50		40		33	MHz
t _{CH}	Clock HIGH	8		10		12		ns
t _{CL}	Clock LOW	8		10		12		ns
t _{AS}	Address Set-Up Before CLK Rise	2		4		5		ns
t _{AH}	Address Hold After CLK Rise	2		3		4		ns
t _{CDV}	Data Output Valid After CLK Rise		14		18		21	ns
t _{DOH}	Data Output Hold After CLK Rise	3		3		3		ns
t _{ADS}	ADSP, ADSC Set-Up Before CLK Rise	3		4		5		ns
t _{ADH}	ADSP, ADSC Hold After CLK Rise	2		3		4		ns
t _{WES}	WE Set-Up Before CLK Rise	3		4		5		ns
t _{WEH}	WE Hold After CLK Rise	2		3		4		ns
t _{ADVS}	ADV Set-Up Before CLK Rise	3		4		5		ns
t _{ADVH}	ADV Hold After CLK Rise	2		3		4		ns
t _{DS}	Data Input Set-Up Before CLK Rise	3		4		5		ns
t _{DH}	Data Input Hold After CLK Rise	2		3		4		ns
t _{CSS}	Chip Select Set-Up	3		4		5		ns
t _{CSH}	Chip Select Hold After CLK Rise	2		3		4		ns
t _{CSOZ}	Chip Select Sampled to Output High Z ^[6, 7]		10		12		14	ns
t _{CSOV}	Chip Select Sampled to Output Valid	3	14	3	18	3	21	ns
t _{EOZ}	OE HIGH to Output High Z ^[6]		7		9		11	ns
t _{EOV}	OE LOW to Output Valid		7		9		11	ns
t _{WEOZ}	WE Sampled LOW to Output High Z ^[6]		10		12		14	ns
t _{WEOV}	WE Sampled HIGH to Output Valid	3	14	3	18	3	21	ns

Notes:

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 85-pF load capacitance.
- t_{CSOZ}, t_{EOZ}, and t_{WEOZ} are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ± 500 mV from steady state voltage.
- At any given voltage and temperature, t_{CSOZ} (t_{WEOZ}) min. is less than t_{CSOV} (t_{WEOV}) min.

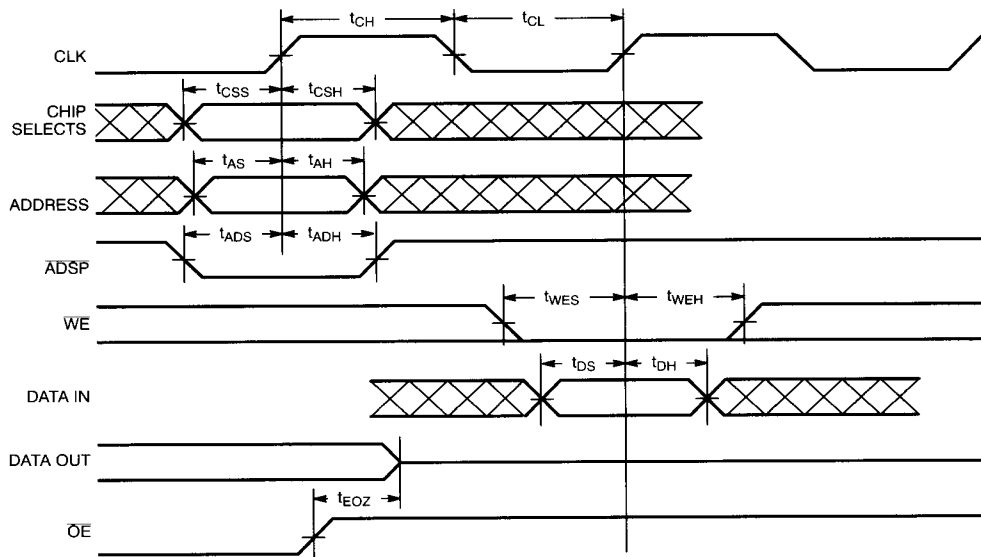
Switching Waveforms

Single Read



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Single 486 Write

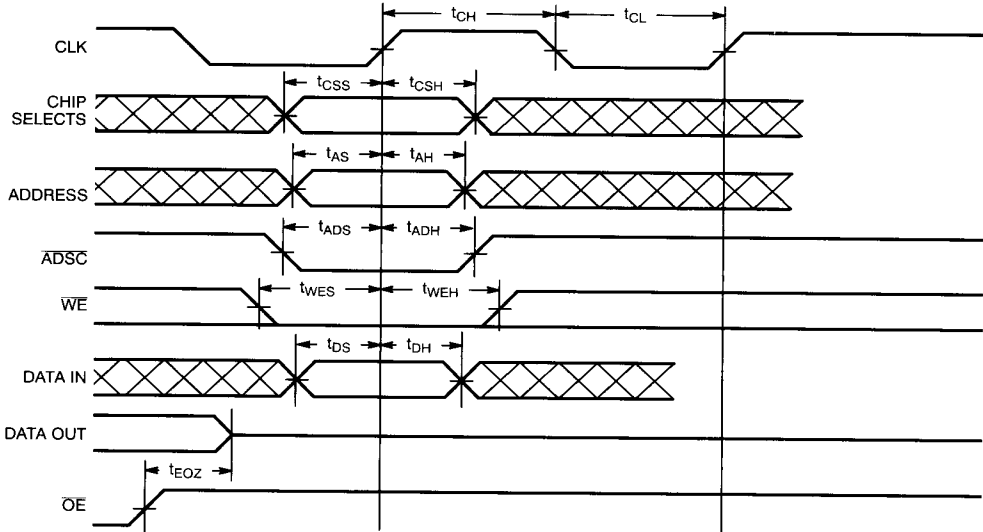


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Switching Waveforms (continued)

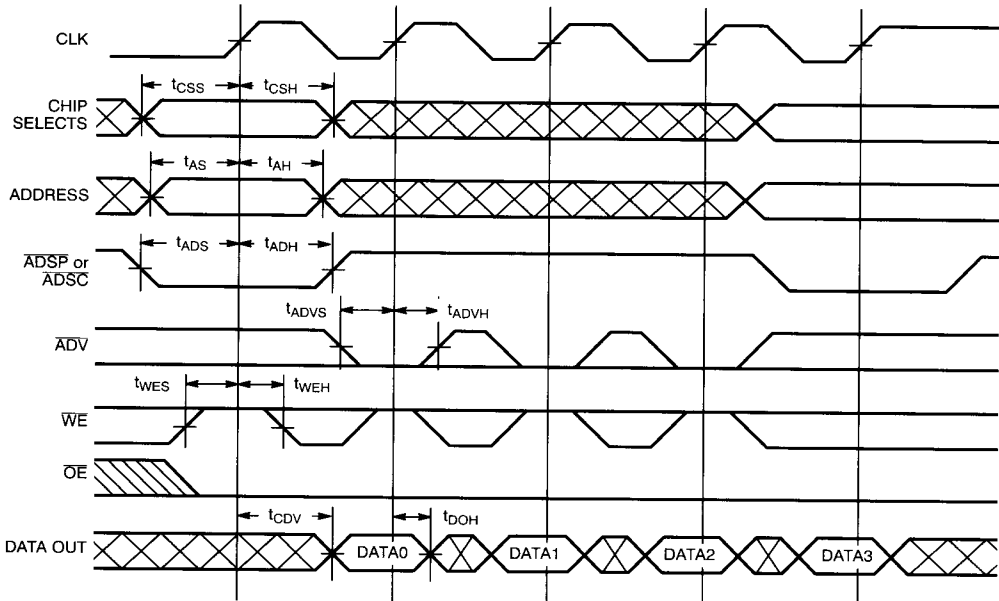
Single Cache Controller Write

2
SRAMs



B173-8

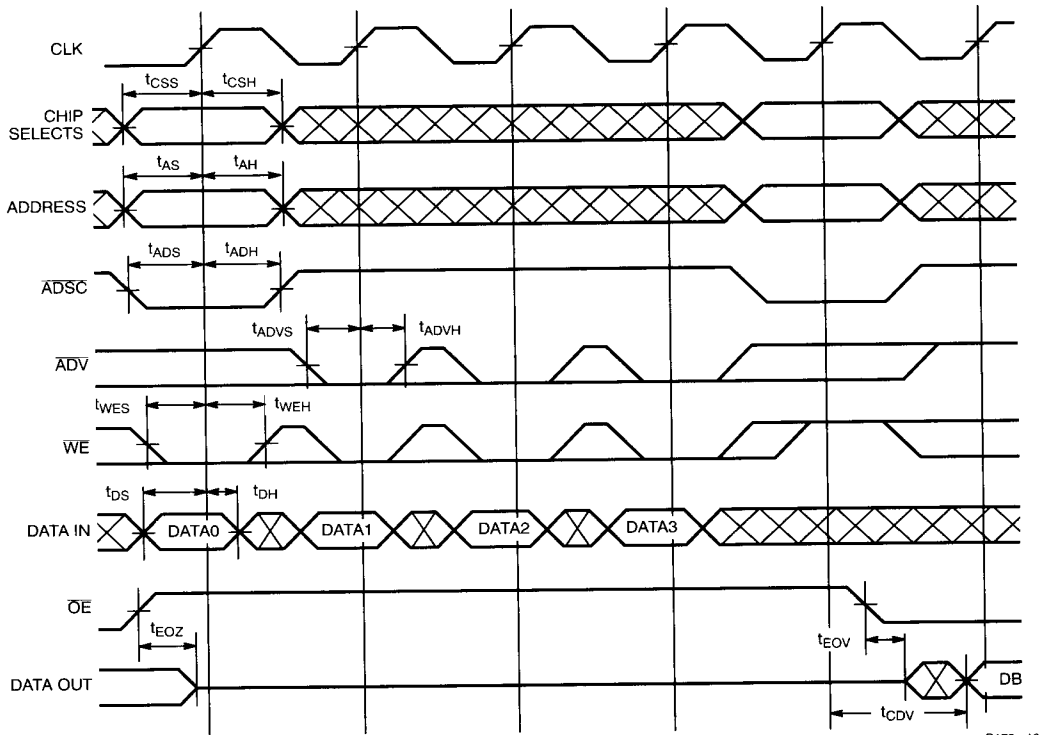
Burst Read Sequence with Four Accesses



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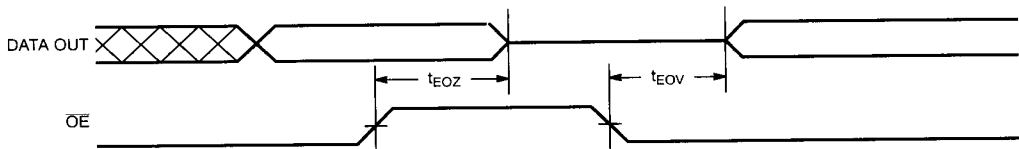
Switching Waveforms (continued)

Cache Controller Burst Write Sequence with Four Accesses Followed by a Single Read Cycle



B173-10

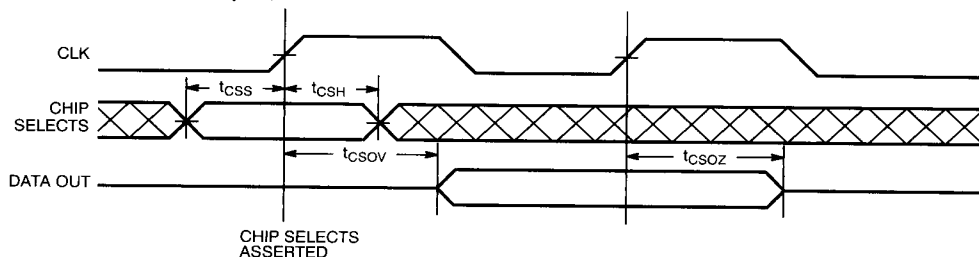
Output (Controlled by $\overline{OE}$)



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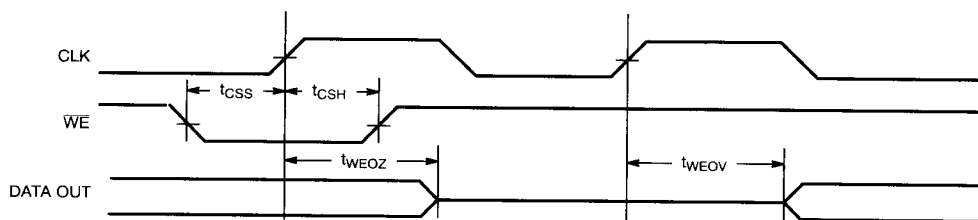
Switching Waveforms (continued)

Output Timing (Controlled by CS)



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Output Timing (Controlled by WE)



B173-13

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
14	CY7B173-14JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
18	CY7B173-18JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
	CY7B173-18LC	L67	44-Square Leadless Chip Carrier	
	CY7B173-18LMB	L67	44-Square Leadless Chip Carrier	Military
21	CY7B173-21JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
	CY7B173-21LC	L67	44-Square Leadless Chip Carrier	
	CY7B173-21LMB	L67	44-Square Leadless Chip Carrier	Military

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
14	CY7B174-14JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
18	CY7B174-18JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
	CY7B174-18LC	L67	44-Square Leadless Chip Carrier	
	CY7B174-18LMB	L67	44-Square Leadless Chip Carrier	Military
21	CY7B174-21JC	J67	44-Lead Plastic Leaded Chip Carrier	Commercial
	CY7B174-21LC	L67	44-Square Leadless Chip Carrier	
	CY7B174-21LMB	L67	44-Square Leadless Chip Carrier	Military

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